



PCN# : P54GAAB  
Issue Date : May. 01, 2015

**Information Only Notification**

This is to inform you that a change is being made to the following products.

This is a minor change that has no impact on product quality, reliability, electrical or mechanical performance. Affected products will remain fully compliant to all published specifications. Notification is being made for informational purposes only and there is no approval required. Products incorporating this change may be shipped interchangeably with existing unchanged products.

Please contact your local Customer Quality Engineer if you have any questions regarding this notification. Alternatively, you may send an email request for information to PCNSupport@fairchildsemi.com.

**Implementation of change:**

Expected First Shipment Date for Changed Product : Apr. 30, 2015

Expected First Date Code of Changed Product :1518

Description of Change (From) :  
Datasheet Change Only:

Update new thermal board layout on Page 2, Note 1 for 175C/W and Logo, trademark, revision.

NOTES:

1.  $R_{\theta JA}$  is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins.  $R_{\theta JC}$  is guaranteed by design while  $R_{\theta CA}$  is determined by the user's board design.



a. 78 °C/W when mounted on a 1 in<sup>2</sup> pad of 2 oz. copper



b. 175 °C/W when mounted on a minimum pad of 2 oz. copper

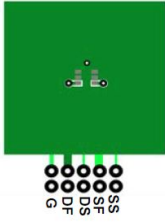
4

Description of Change (To) :

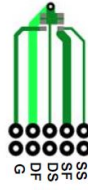
Update new thermal board layout on Page 2, Note 1 for 175C/W and Logo, trademark, revision.

NOTES:

1.  $R_{\theta JA}$  is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins.  
 $R_{\theta JC}$  is guaranteed by design while  $R_{\theta CA}$  is determined by the user's board design.



a. 78 °C/W when mounted on a 1 in<sup>2</sup> pad of 2 oz copper



b. 175 °C/W when mounted on a minimum pad of 2 oz copper

Reason for Change:  
Align thermal board layout contents

Affected Product(s): Please refer to the list of affected products in the addendum attached in the PCN email you received. This list is based on an analysis of your company's procurement history.